



Product Overview

Focus Tech CR-2180 **Copper Reduction Process**

Product Description

The CR-2180 is a hydrogen peroxide/sulfuric acid copper etching process designed to rapidly and evenly reduce copper foil thickness prior to the fine etching operations of HDI and BGA manufacturing processes. CR-2180 offers HDI and BGA manufacturers a cost effective alternative to thin foil laminates by allowing them to accurately and reproducibly reduce 1/2-ounce foil to the optimal thickness for their given process. CR-2180 etches the copper uniformly and often produces a foil thickness with less variation than the starting vendor foil. CR-2180's hydrogen peroxide stabilizers virtually eliminate destabilization losses while etch accelerators and modifiers increase etch rate and improve surface topography.

Features

- ⊙ Produces thin foil laminates to process specific requirements
- ⊙ Rate enhancing additives
- ⊙ Etch modifiers

Benefits

- ⊙ Saves money over the high cost of thin foil laminates and provides process specific foil thickness
- ⊙ Increases etch rate without increasing consumption
- ⊙ Improves surface topography and levels surface

Physical Properties

Specific gravity:	1.0
pH:	6-8
Appearance:	clear to amber color
Freezing point:	<45 °F

Operating Parameters

Copper loading:	40 - 50 g/L as copper metal
Hydrogen peroxide concentration:	6% – 14% (as 35% hydrogen peroxide)
Sulfuric acid concentration:	8% – 14%
Temperature:	80 °F – 100 °F

Safety

Avoid contact with eyes, skin and clothing. Wear chemical handler's gloves, goggles and protective clothing when handling. Read and understand Material Safety Data Sheet before using this product.

Notice

The information and recommendations, contained herein, regarding this product are, to the best of our knowledge, true and accurate. We make no guarantee of results because the conditions of actual use are beyond our control. We assume no liability for damages or penalties resulting from the use of this product or following our recommendations. Our recommendations and suggestions for use of this product are not intended to grant license to operate under or infringe any patent.